Cross-Section View VS1011E
28pin SOIC (RoHS) Package

Device name: VS1011E-S/LSR-ROHS
Marking on device: VS1011E  R
XXXXXXXXXXXXXX YYWW  where YYWW = assembly Year and Week > 0904

Lead Frame
- Plate composition: 100% Sn
- Plate thickness: 500 +/- 50 micro inches average

Material
- Lead Frame: CU194  Ag
- Epoxy Die Attach: CRM 1076NS
- Bonding Wire: 1.0 mil Au
- Mold Compound: EMEG-600